Compliant with IEC 62474/ D9.00

MICROCHIP Semiconductor Device Type: ML (G4X) 020 QFN 4x4x0.9mm Matte Tin			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials				JEDEC 97 Product Marking and/or Pkg. Labeling e3
		"Contained in"	% Total	1						
Basic Substance	CAS Number	Sub-Component	Weight	mg/part	ppm	22.32	(mg) Total	Mold Compound	% ot Total Weight	t 51.79
Silica, fused	60676-86-0	Mold Compound	46.611	20.089	466.110		Silica, fused	60676-86-0	90.00	1
Epoxy Resin	Trade Secret	Mold Compound	2.512	1.083	25,118		Epoxy Resin	Trade Secret	4.85	
Phenolic Resin	Trade Secret	Mold Compound	2.512	1.083	25,118		Phenolic Resin	Trade Secret	4.85	4
Carbon Black	1333-86-4	Mold Compound Mold Compound	0.155	0.067	1,554			1333-86-4	0.30	
	7440-50-8	Lead Frame	35.702	15.388	357.024		Carbon Black			ļ
Copper								Total	100.00	
Iron	7439-89-6	Lead Frame	0.878	0.379	8,782	16.11	(mg) Total	Lead Frame	% of Total Weight	t 37.37
Silver	7440-22-4	Lead Frame	0.712	0.307	7,119		Copper	7440-50-8	95.54	1
Zinc	7440-66-6	Lead Frame	0.047	0.020	467		Iron	7439-89-6	2.35	
Phosphorous	7723-14-0	Lead Frame	0.031	0.013	308		Silver	7440-22-4	1.91	
Silver	7440-22-4	Die Attach	1.053	0.454	10,530		Zinc	7440-66-6	0.13	
Acrylate resins Proprietary	Trade Secret	Die Attach	0.243	0.105	2,430		Phosphorous	7723-14-0	0.08	J
Treated silica	Trade Secret	Die Attach	0.027	0.012	270			Total	100.00	
Heterocyclic organic compound	Trade Secret	Die Attach	0.027	0.012	270	0.58	(mg) Total	Die Attach	% of Total Weight	t_ 1.35
Silicon	7440-21-3	Chip (Die)	4.410	1.901	44,100		Silver	7440-22-4	78.00	
Copper	7440-50-8	Wire Bond Copper Palladium coated (CuPd)	0.629	0.271	6,288		Acrylate resins Proprietary	Trade Secret	18.00	
Palladium	7440-05-3	Wire Bond Copper Palladium coated (CuPd)	0.011	0.005	112		Treated silica	Trade Secret	2.00	1
Tin	7440-31-5	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	4.440	1.914	44,400	Het	erocyclic organic compound	Trade Secret	2.00	
										7
		TOTALS:	100.000	43.100	1,000,000			Total	100.00)
	ith EU Directives	g Total Mass			,,	1.90	Total (mg) Doped Silicon	Total Chip (Die) 7440-21-3	100.00 % of Total Weight 100.00	
semiconductor device and its homogenous materials comply w) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption pliance with the above EU Directives has been verified via inter	ith EU Directives (zero) nal design contro	g Total Mass :: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 Jols, supplier declarations, and /or analytical test data.	lune 2011) and	2015/863/EU (31 March	1.90	1	Chip (Die)	% of Total Weight	t 4.41
and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption bliance with the above EU Directives has been verified via internation nemical substance is absent from the list above, the chemical separated's knowledge and belief as of the date of this document	ith EU Directives (zero) nal design contro ubstance is NOT there is no cred	g Total Mass :: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 Jols, supplier declarations, and /or analytical test data. an intentional ingredient in the semiconductor device and, to tible reason to believe that the unavoidable impurity concents.	lune 2011) and	2015/863/EU (31 March	0.28	1	Chip (Die) 7440-21-3	% of Total Weight	4.41
and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption pliance with the above EU Directives has been verified via intern hemical substance is absent from the list above, the chemical s porated's knowledge and belief as of the date of this document to below the threshold of regulatory concern for any regulatory s ing compounds used by Microchip meet the UL94 V0 flammabil	ith EU Directives (zero) nal design contro ubstance is NOT there is no cred cheme world-wid ity standard for p	g Total Mass :: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 Jols, supplier declarations, and /or analytical test data. an intentional ingredient in the semiconductor device and, to tible reason to believe that the unavoidable impurity concentrice.	June 2011) and the best of M ration of the ch	2015/863/EU (icrochip Tech emical substa	31 March		Doped Silicon	Chip (Die) 7440-21-3 Total Wire Bond Copper Palladium	% of Total Weight 100.00 100.00	4.41
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